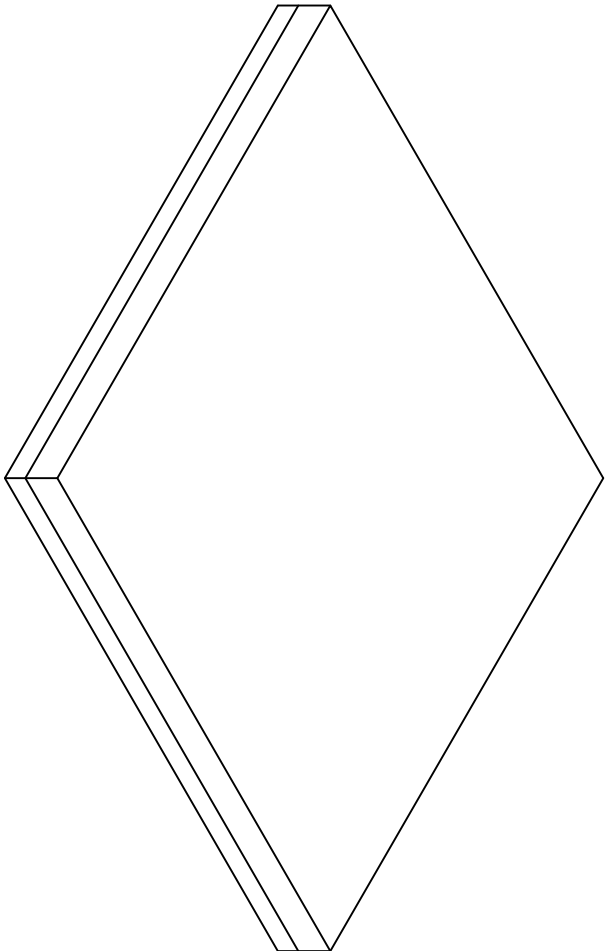


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REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06098	05/06/99	E.B.	M.C.N.
01	ADDED MATRIX, UPDATED NOTES & DIMS	11/02/04	DANIT	DANIT



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 225.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 15 X 15.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		PROJECTION		ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea		AMKOR Electronics, Inc. Chandler, Arizona, USA			
ANGULAR ±1°									
DECIMAL X.X ±0.10 X.XX ±0.05 X.XXX ±0.03		APPROVALS		DATE					
		DRAWN M. NOBLES		04/14/99					
		CHECKED J. MICKSCH		04/29/99					
MATERIAL N/A									
		ENG'R H. BUENAOBRA		04/14/99					
FINISH N/A									
DO NOT SCALE DRAWING		RELEASED G. SCHULTZ		05/06/99					
		TITLE PACKAGE OUTLINE – MAF, 15 X 15 MATRIX, 13.00mm X 13.00mm X 1.10mm, 0.60mm MOLD CAP, 0.80mm PITCH, LAMINATE SUBSTRATE, AWW		SIZE B		SID NUMBER N/A		DWG NUMBER 75442	
		STRIP DWG NUMBER/REV N/A		CUST CODE N/A		SCALE: 8:1		SHEET 1 OF 3	